

# **Quantification of EUV Resist Outgassing**

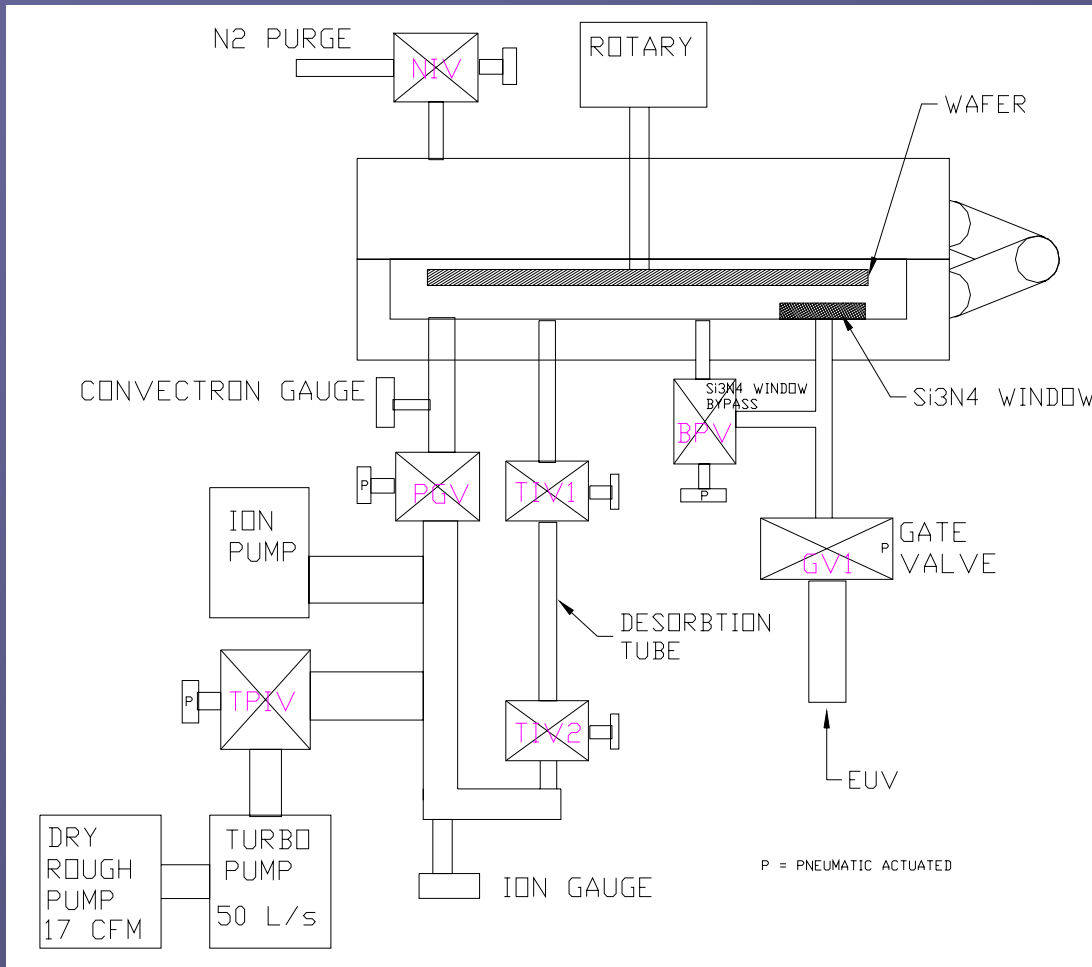
**Heidi B. Cao, Wang Yueh, Vani Thirumala,  
Hokkin Choi**

**Intel Corporation**

**SPIE 2005, Feb 27 - Mar 4**

# Experimental set-up

## Experimental procedure



- Place resist coated wafer in chamber, and pull vacuum.
- Expose resist to EUV.
- Purge chamber with nitrogen into absorption tube.
- Close valve to absorption tube, and remove wafer.
- Repeat with two additional wafers into a single absorption tube to amplify signal.
- Analyze outgassing contaminants using GC/MS.

# Experimental details

- Desorption tubes are packed with a mixture of Tenax and Carboxen resins for sensitivity to hydrocarbons and halogen containing compounds.
- Conversion from area counts to molecules is calculated by introducing a known quantity of an analyte into the GC-MS and characterizing the response.

$$\text{Outgassing Conc (molecules/cm}^2\text{)} = \frac{\text{GC-MS response (Area counts)} / \text{Response Factor (Area count/molecules)}}{\text{Exposed area (cm}^2\text{)}}$$

- We assume that the response of the outgassing species is equivalent to the response of our known standard (toluene).

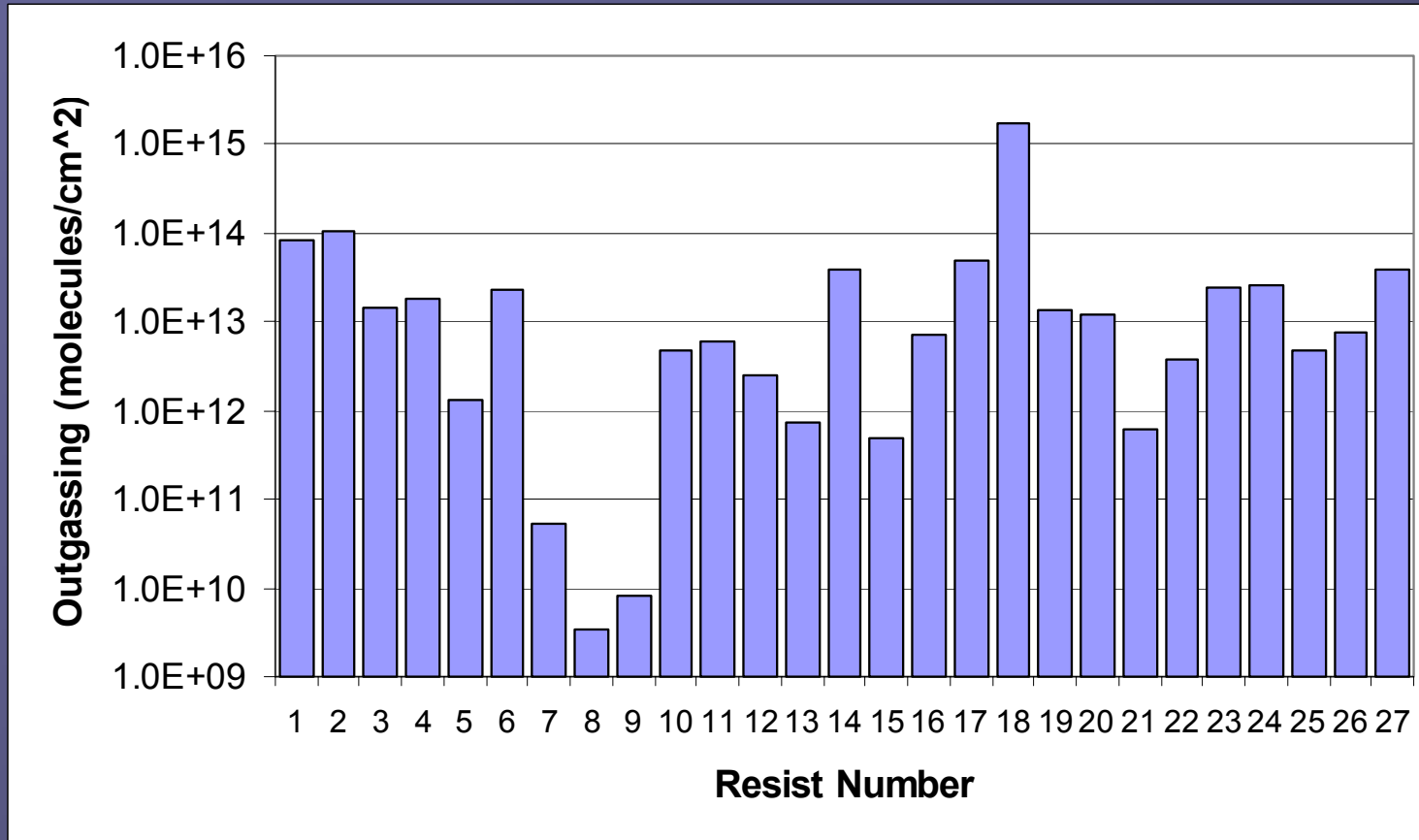
# Limit of detection

- Outgassing can be efficiently measured down to levels of  $10^{11}$  molecules/cm<sup>2</sup>. Below this level, noise from GC/MS and background contaminants is problematic.

Background Contamination Introduced by:	Most Common Background Contamination Observed
GC/MS and empty desorption tube	Silanes
Empty outgassing chamber	Hydrocarbons
Internal standard	Esters

- For each outgassing sample, the empty desorption tube is pre-screened and an empty chamber sample is taken to characterize the background contamination. The background contamination is not included in the final quantification results.

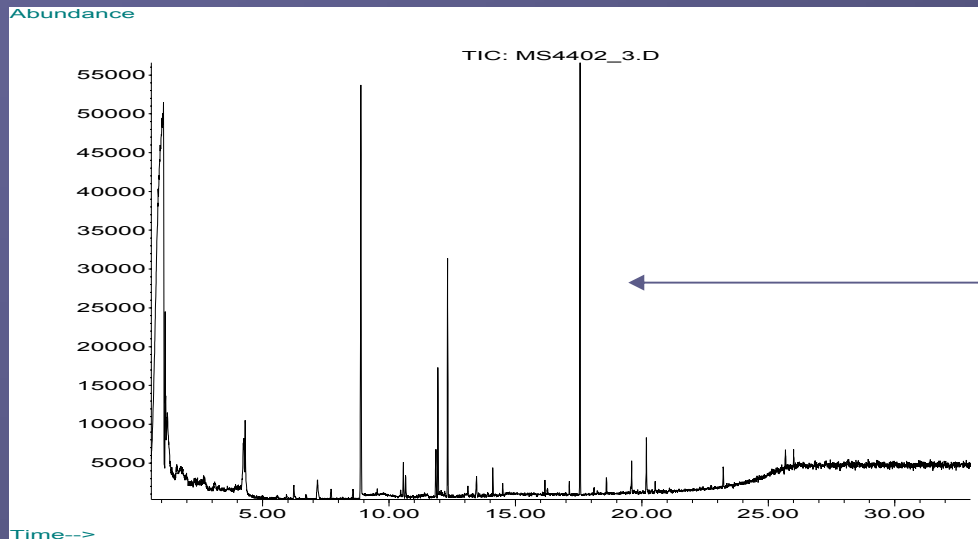
# Levels of outgassing



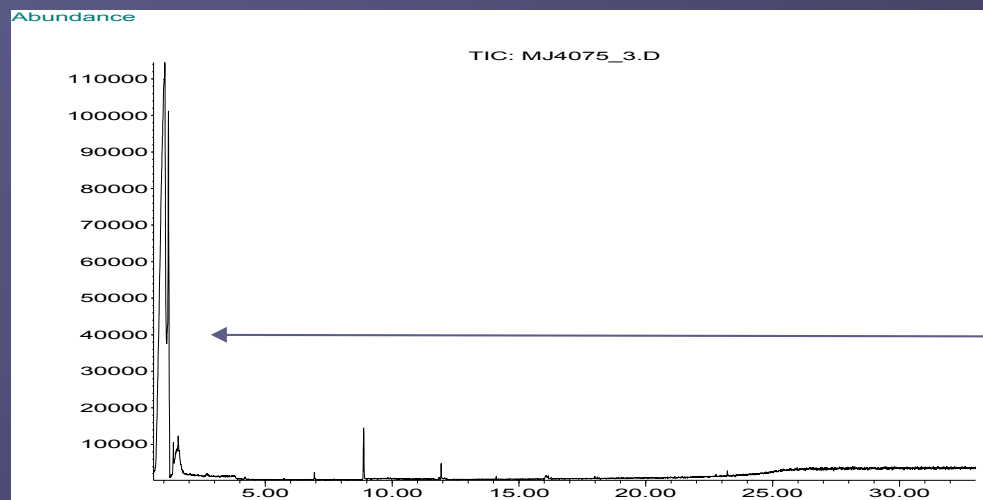
- Resist that have been quantified with outgassing below  $10^{11}$  may not be accurate, since below the detection limit of our technique.

# Outgassing results

- Intel has found the main outgassing contaminants from EUV resists are PAG fragments and protecting groups.



Evidence of PAG  
fragment  
outgassing



Evidence of  
protecting group  
outgassing

# PAG outgassing

Outgassing results as a function of PAG chemistry:

**Ionic PAG A**

$= 1 \cdot 10^{13}$  molecules/cm<sup>2</sup>

**Non-ionic PAG C**

$= 6 \cdot 10^{11}$  molecules/cm<sup>2</sup>

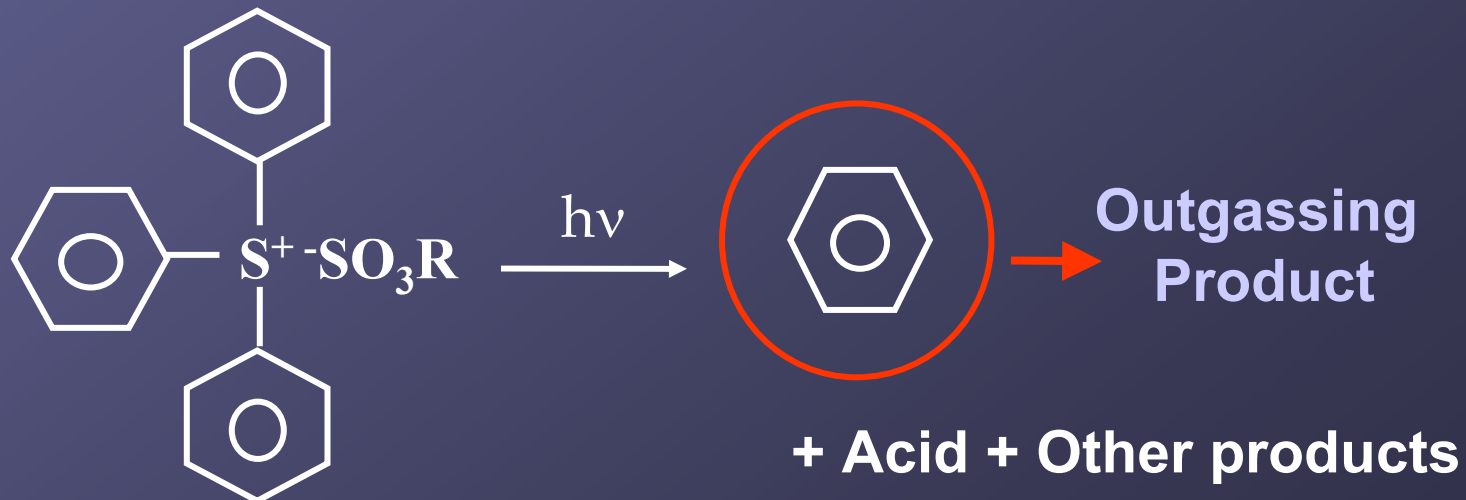
**Ionic PAG B**

$= 6 \cdot 10^{12}$  molecules/cm<sup>2</sup>

**Non-ionic PAG D**

$< 10^{11}$  molecules/cm<sup>2</sup>

Possible outgassing mechanism for an ionic PAG:



# Protecting group outgassing

Outgassing results as a function of activation energy ( $E_{act}$ ) :

Low/medium  $E_{act}$  resist E  
 $= 4 \cdot 10^{13}$  molecules/cm<sup>2</sup>

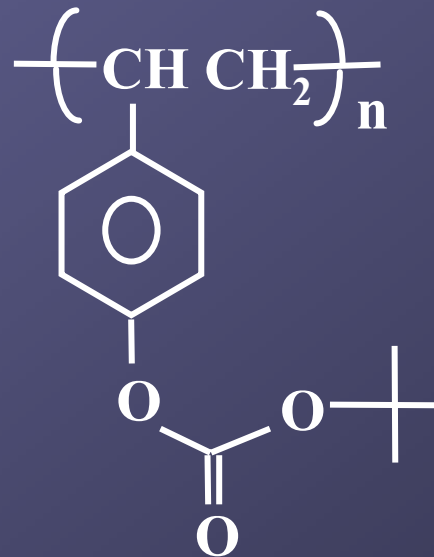
High  $E_{act}$  Resist G  
 $= 7 \cdot 10^{11}$  molecules/cm<sup>2</sup>

Low/medium  $E_{act}$  resist F  
 $= 2 \cdot 10^{13}$  molecules/cm<sup>2</sup>

High  $E_{act}$  Resist H  
 $< 10^{11}$  molecules/cm<sup>2</sup>

Possible deprotecting group outgassing mechanisms:

*T-boc  
 deprotecting  
 group (with  
 medium  
 activation  
 energy) will  
 outgas in EUV.*



Outgassing  
 Products

+ Other products